EcoClean

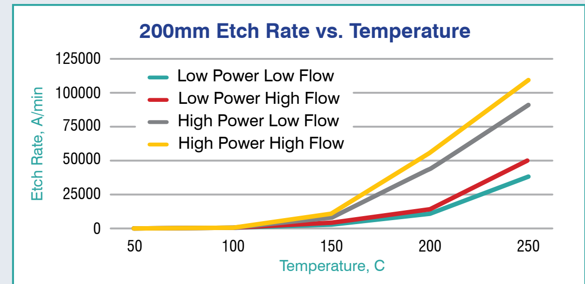
Flexible Plasma Resist Strip/Descum System with Low CoO

- High strip rate and high throughput
- Small footprint with single chamber
- No defects or damage due to ICP downstream plasma
- R&D to high volume production with minimal downtime
- Eco-friendly "green" process

Highly Controlled Removal Rate
100 to 100,000 Å/min
Up to 65 wph process
2-5x faster,
½ the capital cost

Creating advanced solutions for present and next-generation technologies, the EcoClean system offers engineers flexibility and reliability for wafers:

- Photoresist removal
- PR descum
- Polyimide removal
- Organics removal
- Copper oxide removal



Yield Engineering Systems (YES) has designed the EcoClean as a high throughput, low-cost of ownership, single-wafer photoresist removal system. The ICP remote source generates atomic oxygen which chemically reacts with the photoresist of the wafer surface. By employing a downstream resist strip process, high removal rate is achieved with no electrical damage or defects to the substrates and devices. EcoClean offers automated processing with low gas usage and is an eco-friendly "green" solution.

MEMS
LED
MicroLED
Advanced Packaging
Power Devices
Sensors

Contact Us: We offer process demonstrations. If you would like to submit samples, please call us. We can run your samples and provide a detailed process report.

Yield Engineering Systems, Inc.

Call: **1-510-954-6889** (worldwide) or **1-888-YES-3637** (US toll free)

www.yieldengineering.com

EcoClean

SPECIFICATIONS

	SPECIFICATIONS		REMARKS
PERFORMANCE	**Descum Specifications**		
	Approx. Ash Rate	100-1000 Å/min	
	Uniformity	Within wafer: ≤±10%	
	Photoresist Strip Rate		
	Strip Rate	≥5 µm/min	Temperature and photo resist dependent ≥10 µm/min @250C
	Uniformity	Within wafer: ≤ ±10%	
	Wafer Per Month	At least ≥20K / month	The process time including load and unload
HARDWARE	Wafer Temperature Range	75° to 300° C	
	WiW temp Uniformity	±1.5%	5 point TC wafer measured at 200° C
	Capacity	Single wafer/50mm-150mm	Capable of up to 200mm wafer
	Process Gas Inputs	2 MFCs standard (Oxygen and Nitrogen), 3rd forming gas MFC optional	
	O2 MFC	2000 sccm	
	N2 MFC	200 sccm	
	Base Pressure	≤50 mTorr	With 350cfm Ebara Dry Pump (EV-S100)
	Leak Rate	≤ 20 mTorr/min	
	RF Power	500W - 3000W	
SOFTWARE	User Interface	PC with touch screen monitor and pull-out keyboard, barcode reader	
	SECS/GEM	Optional	
	Operating System	Windows 10 Currently supports wired Ethernet communication	

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